
Preskusne metode za električne materiale, tiskana vezja in druge povezovalne strukture in sestave - 2-719. del: Preskusne metode za tiskana vezja in montažni material - Relativna permitivnost in tangenta izgub (500 MHz do 10 GHz)

Test methods for electrical materials, printed board and other interconnection structures and assemblies - Part 2-719: Test methods for printed board and assembly materials - Relative permittivity and loss tangent (500MHz to 10GHz)

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Méthodes d'essai pour les matériaux électriques, les cartes imprimées et autres structures d'interconnexion et ensembles - Partie 2-719: Méthodes d'essai pour les cartes imprimées et les matériaux d'assemblage - Permittivité relative et tangente de perte (500 MHz à 10 GHz)

Ta slovenski standard je istoveten z: EN 61189-2-719:2016

ICS:

31.180	Tiskana vezja (TIV) in tiskane plošče	Printed circuits and boards
31.190	Sestavljeni elektronski elementi	Electronic component assemblies

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EUROPEAN STANDARD

EN 61189-2-719

NORME EUROPÉENNE

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October 2016

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English Version

Test methods for electrical materials, printed boards and other
interconnection structures and assemblies -
Part 2-719: Test methods for materials for interconnection
structures - Relative permittivity and loss tangent (500 MHz to 10
GHz)
(IEC 61189-2-719:2016)

Méthode d'essai pour les matériaux électriques, les cartes
imprimées et autres structures d'interconnexion et
ensembles - Partie 2-719: Méthodes d'essai des matériaux
pour structures d'interconnexion - Permittivité relative et
tangente de perte (500 MHz à 10 GHz)
(IEC 61189-2-719:2016)

Prüfverfahren für Elektromaterialien, Leiterplatten und
andere Verbindungsstrukturen und Baugruppen -
Teil 2-719: Prüfverfahren für Materialien von
Verbindungsstrukturen - Relative Permittivität und
Verlustfaktor (500 MHz bis 10 GHz)
(IEC 61189-2-719:2016)

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European Committee for Electrotechnical Standardization
Comité Européen de Normalisation Electrotechnique
Europäisches Komitee für Elektrotechnische Normung

CEN-CENELEC Management Centre: Avenue Marnix 17, B-1000 Brussels

EN 61189-2-719:2016**European foreword**

The text of document 91/1366/FDIS, future edition 1 of IEC 61189-2-719, prepared by IEC/TC 91 "Electronics assembly technology" was submitted to the IEC-CENELEC parallel vote and approved by CENELEC as EN 61189-2-719:2016.

The following dates are fixed:

- latest date by which the document has to be implemented at national level by publication of an identical national standard or by endorsement (dop) 2017-05-16
- latest date by which the national standards conflicting with the document have to be withdrawn (dow) 2019-08-16

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Annex ZA (normative)

Normative references to international publications with their corresponding European publications

The following documents, in whole or in part, are normatively referenced in this document and are indispensable for its application. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

NOTE 1 When an International Publication has been modified by common modifications, indicated by (mod), the relevant EN/HD applies.

NOTE 2 Up-to-date information on the latest versions of the European Standards listed in this annex is available here: www.cenelec.eu

<u>Publication</u>	<u>Year</u>	<u>Title</u>	<u>EN/HD</u>	<u>Year</u>
IEC 60194	-	Printed board design, manufacture and assembly - Terms and definitions	-	-

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**Test methods for electrical materials, printed boards and other interconnection structures and assemblies –
Part 2-719: Test methods for materials for interconnection structures – Relative permittivity and loss tangent (500 MHz to 10 GHz)**

<https://standards.iteh.ai/catalog/standards/sist/2ac1bb3e-3704-4121-bb1d-57a261571c16/en-61189-2-719:2017>

**Méthode d'essai pour les matériaux électriques, les cartes imprimées et autres structures d'interconnexion et ensembles –
Partie 2-719: Méthodes d'essai des matériaux pour structures d'interconnexion – Permittivité relative et tangente de perte (500 MHz à 10 GHz)**

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INTERNATIONAL ELECTROTECHNICAL COMMISSION

**TEST METHODS FOR ELECTRICAL MATERIALS, PRINTED BOARDS AND
OTHER INTERCONNECTION STRUCTURES AND ASSEMBLIES –****Part 2-719: Test methods for materials for interconnection structures –
Relative permittivity and loss tangent (500 MHz to 10 GHz)**

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International Standard IEC 61189-2-719 has been prepared by IEC technical committee 91: Electronics assembly technology.

The text of this standard is based on the following documents:

FDIS	Report on voting
91/1366/FDIS	91/1380/RVD

Full information on the voting for the approval of this standard can be found in the report on voting indicated in the above table.

This publication has been drafted in accordance with the ISO/IEC Directives, Part 2.

A list of all parts in the IEC 61189 series, published under the general title *Test methods for electrical materials, printed boards and other interconnection structures and assemblies*, can be found on the IEC website.

The committee has decided that the contents of this publication will remain unchanged until the stability date indicated on the IEC website under "<http://webstore.iec.ch>" in the data related to the specific publication. At this date, the publication will be

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- withdrawn,
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